

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Ichitsubo

Application No.: 10/804,737

Filed: 3/18/2004

Examiner: Lewis, Monica

Art Unit: 2822

RESPONSE

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

Applicants submit this Response to the Office Action mailed 6/6/2007. The Office Action rejected claims 1-9, 11, 14 and 19-20 under 35 U.S.C. 103(a) as unpatentable over U.S. Patent No. 6,642,617 (Kawai) in view of Active Substrates (Riches) and USPN 5,628,919 (Tomura). Claim 3 was rejected under 35 U.S.C. 103(a) as being unpatentable over Kawai in view of Riches, Tomura and Lin. Claim 10 was rejected under 35 U.S.C. 103(a) as being unpatentable over Kawai in view of Riches, Tomura, and *Electronic Packaging and Interconnection Handbook* by Charles A. Harper (Harper). Claims 12 and 13 were rejected under 35 U.S.C. 103(a) as being unpatentable over Kawai in view of Riches, Tomura, *Microchip Fabrication* by Peter Van Zant (van Zant). Claims 15 and 16 were rejected under 35 U.S.C. 103(a) as being unpatentable over Kawai in view of Riches, Tomura, and Pohjonen (U.S. Patent No. 6,462,950). Claim 17 was rejected under 35 U.S.C. 103 (a) as being unpatentable over Kawai in view of Riches, Tomura, Pohjonen and Van Zant. Claim 18 was rejected under 35 U.S.C. 103(a) as being unpatentable over Kawai in view of Riches, Tomura, Apel (U.S. Patent No. 6,727,761).

In view of the reasons set forth below, Applicants submit that all claims are in condition for allowance and respectfully submit allowance of all claims.